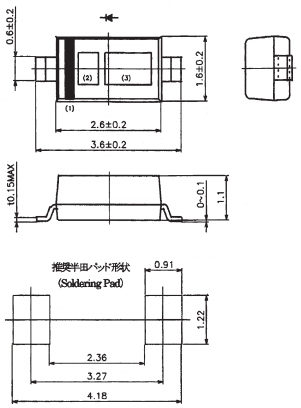
0.5A Avg. 200 Volts FRED EP05FA20

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	200			V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	Ta＝25℃*	0.45	A
			Tl＝115℃	0.5	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	0.785			A
サージ順電流 Surge Forward Current	I_{FSM}	8 50Hz正弦半波，1サイクル，非くり返し 50Hz Half Sine Wave,1cycle, Non-repetitive			A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40〜＋150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40〜＋150			℃

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.011g

■電気的・熱的特性 Electrical/Thermal Characteristics

Characteristic	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	Tj＝25℃, V_{RM}＝ V_{RRM}	—	—	10	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	Tj＝25℃, I_{FM}＝0.5A	—	—	0.95	V
逆回復時間 Reverse Recovery Time	trr	I_{FM}＝0.5A, -di/dt＝50 A/μs, T_j＝25℃	—	—	30	ns
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間* Junction to Ambient*	—	—	300	℃/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	70	℃/W

＊プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 1×1 mm , Both Sides)

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

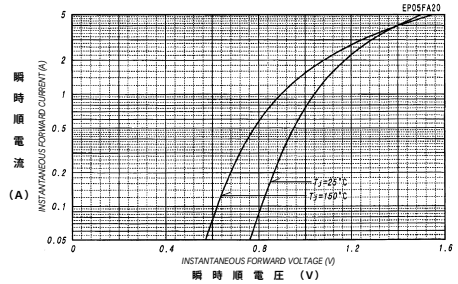


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

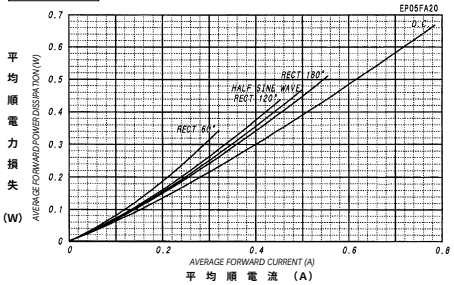


FIG.3
平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy Substrate Mounted(Soldering Land=1×1mm)

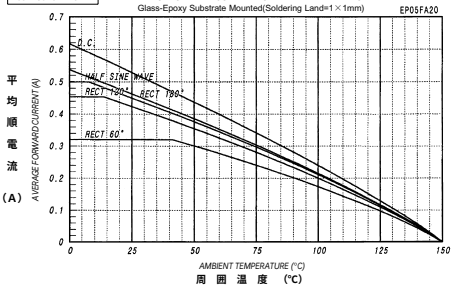


FIG.4
平均順電流－リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

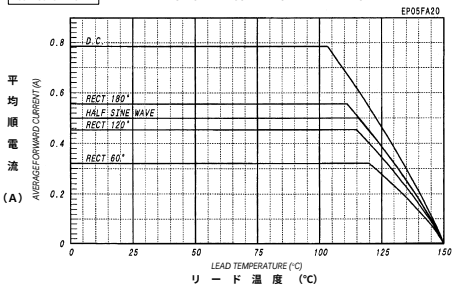


FIG.5
サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz,Half Sine Wave,Non-repetitive,No Load

